



HIGH SPECIFICATION PRODUCTS

Product Data Sheet

HSP-CF-H Rigid Conductive Foam

Grade

HSP-CF-H

Issue Number

1

Date

1st December 2010

Description: A semi rigid electronically conductive foam

Uses: Physical and static protection of integrated circuits via pin insertion

<i>Property</i>	<i>Typical Value</i>
Foam Type	Polyether based Polyurethane impregnated With a carbon loaded rigid latex
Density	>50Kg/m ³
Surface Resistance	10 ⁴ Ohms
Volume Resistance	30 Ohm m
Compression Set	25%
Colour	Black
Format	Sheets / Rolls Cut parts

Additional Notes:

HSP-CF-H is non corrosive, non shedding and non marking

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